



BGA / LGA / QFN / QFP Test Contact Probe (Unit : mm)

## Applications

- BGA / LGA / QFN / QFP package function test.
- BGA / LGA / QFN / QFP package burn-in test.

## Features

- Superior high frequency performance matches with high speed testing.
- High performance, high durability and high reliability short spring probe.
- In-house micron technology can realize stable contact resistance.

## Specifications

Pitch	0.3mm ~ 1.27mm
Probe Length	1.0mm ~ 5.05mm
Operating Temperature	-55°C ~ +125°C(+150°C)*

\* Customized for 150°C case